

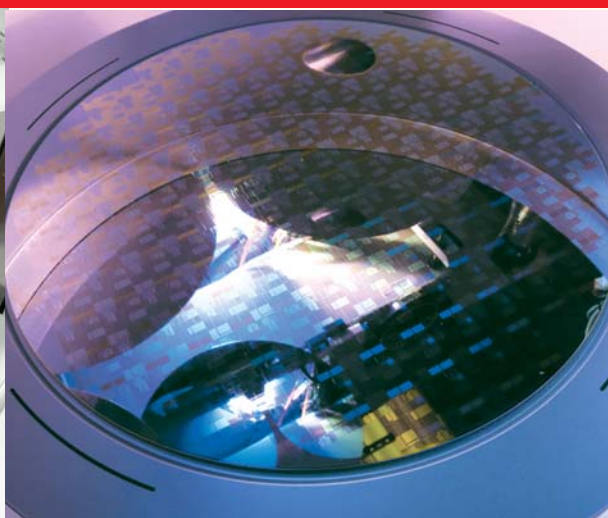
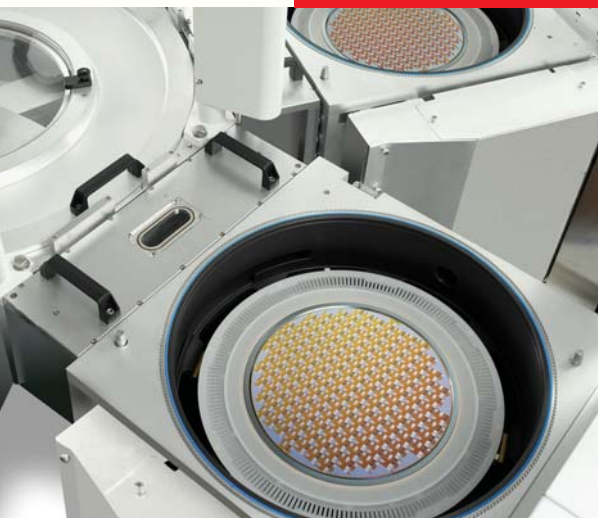
半导体科技

制封测 · 造装试

**SolidState
TECHNOLOGY**
THE INTERNATIONAL MAGAZINE FOR SEMICONDUCTOR MANUFACTURING

**Advanced
Packaging**
THE INTERNATIONAL MAGAZINE FOR ELECTRONIC PACKAGING APPLICATIONS

CHINA



FOR
THE

www.ap-china.com www.solidstatechina.com

媒体信息 Media Information

ACT



概述 Introduction

由雅时国际商讯ACT International主办出版的《半导体科技 SST-AP China》杂志已经创刊逾10年。2011年《半导体科技》将出版6期（双月刊）。《半导体科技》获得世界知名品牌杂志《Solid State Technology》和《Advanced Packaging》的版权许可，独家以简体中文翻译其内容并出版和发行。

《半导体科技》提供半导体业界最新新闻、信息、深度分析和权威评论。每期杂志印刷出版9,000册，同时发行网络版电子杂志和在线杂志网站，为中国半导体行业专家、工程师和技术工程经理，提供决策和采购需要的最新技术、市场资讯及商业采购信息。

《半导体科技》覆盖半导体制造、先进封装、晶圆代工、集成电路、薄膜微电子、平板显示器、纳米技术、工艺及设备等内容。

《半导体科技》服务于整个半导体供应链，包括经销商、制造商、代工厂、行业协会或联盟、研发组织、混合电路、专用ASIC、半导体制造和测试设备、材料、IC封装，以及政府及教育机构。

Established for more than 10 years, SST-AP China magazine -- published by ACT International - will be produced six times (bi-monthly) in 2011. SST-AP China has been granted an exclusive license by world-renowned titles Solid State Technology and Advanced Packaging to translate and circulate editorial content in a simplified Chinese edition.

Through our publication we provide the latest semiconductor news, in-depth analysis and authoritative commentary. Each issue of SST-AP China will have a print run of 9,000 copies supplemented by the web-based e-magazine and online operation, providing our qualified China semiconductor professionals with the business and product information they need to make informed purchasing decisions.

SST-AP China covers semiconductor manufacturing, advanced packaging, wafer fabrication, integrated circuits, thin-film microelectronics, flat-panel displays, and nanometer technologies, processes and equipment and more.

The publication serves the entire semiconductor supply chain which includes merchant and captive manufacturers, foundries, consortiums, R&D operations, hybrid circuits, ASICs, semiconductor manufacturing and test equipment, materials, IC packaging, as well as government and educational institutions.

全方位信息平台 Completed Information Platform

印刷杂志 Print Magazine



中文简体版
Simplified Chinese Edition



英文版
English Edition

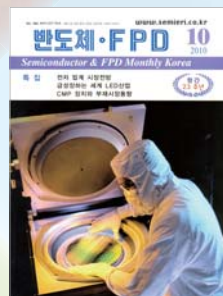
电子媒体 Digital Media



网站 Website



网上论坛 Online Forum
www.mychipchina.com



韩文版
Korea Edition



中文繁体版
Traditional Chinese Edition



电子快讯 eFocus



电子书 eMagazine

晶芯先进技术研讨会系列 CHIP China Technical Conference Series

CHIP China
晶芯研讨会

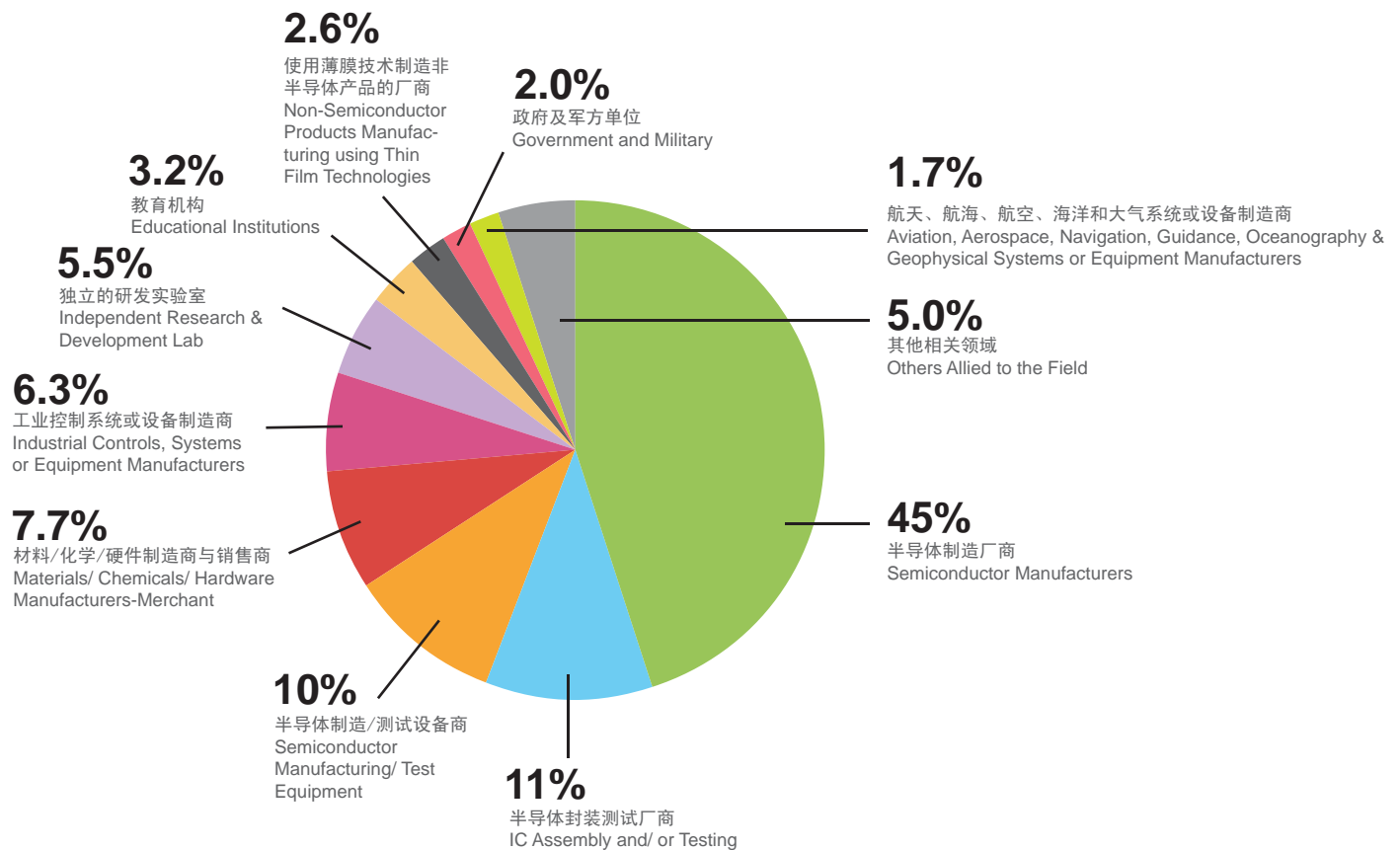


发行 Circulation

《半导体科技》主要采用读者申请、免费赠阅的方式发行，并在很多专业展览和会议上向观众免费派发。印刷版每期发行量为 9,045 册，电子版送达更多专业读者。读者分布情况如下：

SST-AP China is distributed controlled-free to the qualified readers, with bonus distribution at major trade shows/ conferences in China. Total circulation for print magazine is 9,045, digital magazine reaches much larger base of audiences. The circulation breakdown is as following.

按读者所在单位类型 By Business/ Industry



按读者的工作性质 By Job Functions

半导体制造; 工艺; 研发 Semiconductor Manufacturing; Processing; R&D	51.3%
公司运营和工程管理 General/ Corp and Engineering Management	19.8%
工程技术支持; 工厂/ 设备/ 维护工程 Engineering Support; Plant/ Facilities/ Maintenance Engineering	14.3%
可靠性, 品质控制, 评估和测试 Reliability, Quality Control, Evaluation, Testing	6.0%
采购 Purchasing	3.6%
咨询 Consulting	1.5%
其他 Others Allied to the Field	3.5%
	100%

按地区分布 By Geographical

华东 East China	53.3%
华南 South China	18%
华北 North China	16%
东北 Northeast China	2.9%
西南 Southwest China	3.6%
华中 Central China	2.8%
西北 Northwest China	2.6%
香港 Hong Kong	0.8%
	100%

广告价格 Advertising Rate (美元 US\$)

	1x			3x			6x			9x			12x		
整版 Full Page	3,220	2,840	2,600	3,090	2,720	2,470	2,970	2,600	2,350	2,850	2,470	2,220	2,730	2,360	2,110
2/3 版 Page 横/纵 H/V	2,510	2,140	1,890	2,420	2,040	1,790	2,340	1,960	1,710	2,220	1,850	1,600	2,130	1,760	1,510
1/2 版 Page 岛形 Island	2,350	1,970	1,720	2,260	1,890	1,640	2,170	1,790	1,540	2,070	1,690	1,440	1,980	1,610	1,360
1/2 版 Page 横/纵 H/V	2,260	1,890	1,640	2,170	1,790	1,540	2,080	1,700	1,450	1,990	1,620	1,370	1,910	1,530	1,280
1/3 版 Page 横/纵 H/V	1,780	1,410	1,160	1,730	1,360	1,110	1,680	1,310	1,060	1,620	1,240	990	1,560	1,180	930
1/4 版 Page	1,520	1,150	900	1,490	1,120	870	1,440	1,070	820	1,400	1,020	780	1,350	970	720
1/6 版 Page	1,260	890	640	1,240	870	620	1,210	840	590	1,190	820	570	1,130	750	510

封面内页 Cover II	5,600	第一页 P. 1	4,330	广告公司佣金15% 15% commission to recognized ad agency
封底内页 Cover III	4,330	目录对页 Facing Table of Content	3,960	翻译 Translation charge: US\$100/ page页
封底 Cover IV	5,610	其他特别位置 Other Specified Positions	+10%	

网上广告价格 Online Advertising

网站 Website	横幅 Banner	尺寸 Dimension (pixels, w x h)	大小 Size	月/ Month US\$	No. of Ads to rotate
	R 1	180 x 150	40K	1,400	2
	R 2	180 x 150	40K	1,400	2
	R 3 (skyscraper)	180 x 600	100K	1,400	2
	R 4, 5, 6	180 x 150	60K	500	2
	Leaderboard (top banner)	728 x 90	100K	1,400	3
	Anchor (bottom banner)	728 x 90	100K	1,000	3
	Prime Products ¹ 精品推介 (2 weeks)	140 x 100	60K	400	N/A
	Logo Sponsor ²	160 x 60	20K	300	N/A

1. Product picture on homepage top middle and highlighted text link in product section for two weeks
产品图片在首页的顶部中间，及标示的文字连结在产品栏目中两周

2. Max 15 company logo to be displayed randomly on 10 buttons space
最多15家公司徽标，随机显示10个按钮的空间

*Exclusive banner add 50%, exclusive top/bottom banner add 100%
独家横幅位置增加50%，独家top/bottom 横幅位置增加100%

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电子快讯 eFocus

位置 Position	尺寸 Dimension (pixels, w x h)	大小 Size	格式 Format	月/ Month US\$
Top Banner	728 x 90	60K	JPG/ GIF	1,400
Banner 1	300 x 60	30K	JPG/ GIF	900
Banner 2	300 x 60	30K	JPG/ GIF	700
Banner 3	300 x 60	30K	JPG/ GIF	700
Text Ad 1	Max. 110 Chinese words		Word doc.	900
Text Ad 2	Max. 110 Chinese words		Word doc.	700
Video Snapshot 1		N/A		1,000
Video Snapshot 2		N/A		1,000
Video Snapshot 3		N/A		700

电子杂志 eMagazine



位置 Position	月/ Month US\$	备注 Remark
eMagazine download	650	per issue (max.2 sponsors)
Notice---Sponsor logo	900	per issue (exclusive sponsor)
Login page---Text ad	450	per month (max. 2 ads)
Select issue---Sponsor logo	650	per month (max. 2 sponsors)
Refer a friend---Text ad	350	per month (max. 2 ads)
Menu Bar (all pages)--- Sponsor logo	800	per issue (max. 2 sponsors)
Enhanced Ad (adding web functions to print ad) 电子广告增值(加入电子功能)	月/ Month US\$	备注 Remark
Web-link (one) 连结 (一个)	Free 免费	
Web-link (each additional) 连结 (每增加一个)	30	
Add-on Flash function 加入Flash 功能	650	(incl. production 包括制作)
Add-on Button with web-links 加入Button (含连结)	250	(incl. production 包括制作)
Add-on additional Full Page ad 增加整版广告	650	(full page only 只接受整页)

电子快讯 eFocus

Top Banner 728x90

Banner 1 300x60

Banner 2 300x60

Banner 3 300x60

Text ad 1

Text ad 2

电子快讯编辑计划 eFocus Editorial Calendar

主题/ Theme	主题/ Theme
1 * 2011 产业展望 2011 Outlook * 先进 Cu 互连 Advanced Copper Interconnecting	7 * 清洗 Cleaning * 晶圆凸点 Wafer Bumping
2 * 光刻 Lithography * 3D 集成 3D Integration	8 * 柔性电子 Flex-electronics * 互连 Interconnect
3 * 检测 Metrology * 太阳能/ 光伏 Photovoltaics	9 * 3D 封装 3D Packaging * 太阳能电池 Solar Cells
4 * 清洗 Cleaning * 芯片堆叠 Die Stacked	10 * 底部填充 Underfill * 晶圆探测 Wafer Probing
5 * 测试与检查 Test & Inspection * 刻蚀 Etch	11 * 太阳能/ 光伏 Photovoltaics * 硅通孔 TSV
6 * 3D 封装 3D Packaging * 薄膜光伏技术 Film Technology for Photovoltaics	12 * 堆叠式封装 Packaging on Packaging (PoP) * 倒装芯片 Flip Chips

※ 欢迎投稿 Submissions welcomed

规格 Mechanical Specifications

	跨版 Spread Page	整版 Full Page	2/3 版纵向 Vertical	2/3 版横向 Horizontal	1/2 版纵向 Vertical	1/2 版横向 Horizontal	1/2 版岛形 Island	1/3 版纵向 Vertical	1/3 版横向 Horizontal	1/4 版	1/6 版	
有效面积 Live Area (Non-Bleed)												
裁切尺寸 (Trim)	381mm x 254mm 15" x 10"	178mm x 254mm 7" x 10"	114mm x 248mm 4.5" x 9.75"	178mm x 168mm 7" x 6.61"	86mm x 248mm 3.375" x 9.75"	178mm x 124mm 7" x 4.875"	114mm x 187mm 4.5" x 7.375"	57mm x 248mm 2.25" x 9.75"	178mm x 84mm 7" x 3.31"	86mm x 124mm 3.375" x 4.875"	57mm x 124mm 2.25" x 4.875"	
出血尺寸 (Bleed)	406mm x 273mm 16" x 10.75"	203mm x 273mm 8" x 10.75"	※ 有效面积: 包括所有广告内容 (文字, 图像和照片) Live Area: Including all essential elements (text, graphics & photos)					70mm x 273mm 2.76" x 10.75"				
	419mm x 279mm 16.45" x 11"	209mm x 279mm 8.25" x 11"						76mm x 279mm 2.99" x 11"				

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Send your booking orders & ad materials by email, courier or FTP upload. Contact Mandy for details. 请通过电邮, 速递或FTP上传提交广告订单及物料。若有需要请联系Mandy

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编辑计划 Editorial Calendar

月份 Issue	前道 Front End	后道 Back End	展会赠阅 Bonus Distribution
<p>2/3</p> <p>Issue date: 25/2 Ad close: 11/2 Mat close: 19/2 Editorial: 1/2</p>	<ul style="list-style-type: none"> 太阳能电池制技术 Solar Cell Manufacturing 检测 Metrology 平板显示 FPD Technology 气体/化学品 Gases/ Chemicals 	<ul style="list-style-type: none"> 硅通孔 TSV 晶圆凸点 Wafer Bumping 焊料 Solders 封装检查 Packaging Inspection 	<ul style="list-style-type: none"> ※ SEMICON China 上海/ Shanghai 3月 ※ SOLARCON China 上海/ Shanghai 3月 ※ FPD China 上海/ Shanghai 3月
	<p>特别项目 Special Activities</p> <p>※ 企业/产品介绍 Corporate Profile Issue ※ SEMICON China 产品预览 SEMICON China Products Showcase</p>		
<p>4/5</p> <p>Issue date: 27/4 Ad close: 12/4 Mat close: 19/4 Editorial: 1/4</p>	<ul style="list-style-type: none"> 光刻 Lithography 先进Cu互连 Advanced Cu Interconnecting 材料 Materials 提高太阳能电池效率 Improving solar cell efficiency 	<ul style="list-style-type: none"> 分送、底部填充、涂覆 Dispensing, Underfill, Coating 导热材料 Thermal Issue 贴片 Die Attach 3D 集成 3D Integration 	<ul style="list-style-type: none"> ※ 亚洲太阳能光伏工业展览会 Asia Solar 上海/ Shanghai 5月 ※ 中国国际电子生产设备暨微电子工业展览会 Nepcon China 上海/ Shanghai 5月 ※ The ConFab 拉斯维加斯/ Las Vegas 5月 ※ SEMI FPD Expo 台湾/ Taiwan 6月
	<p>特别项目 Special Activities</p> <p>※ SEMICON China/ SOLARCON China 会后采访报道 SEMICON China/ SOLARCON China Show Report</p>		
<p>6/7</p> <p>Issue date: 21/6 Ad close: 1/6 Mat close: 10/6 Editorial: 20/5</p>	<ul style="list-style-type: none"> 高k金属栅 High-k Metal Gate (HKMG) 刻蚀 Etch 真空技术 Vacuum Technology 清洗 Cleaning 	<ul style="list-style-type: none"> 晶圆级封装 Wafer-level Packaging 测试与检查 Test and Inspection 堆叠式封装 (PoP) Packaging on Packaging (PoP) 倒装芯片 Flip Chips 	<ul style="list-style-type: none"> ※ SEMICON West 旧金山/ San Francisco 7月
<p>8/9</p> <p>Issue date: 20/8 Ad close: 1/8 Mat close: 10/8 Editorial: 20/7</p>	<ul style="list-style-type: none"> 光刻 Lithography 低k材料;气隙 Low-k Dielectrics; Air Gaps 先进工艺控制 Advanced Processing Control 薄膜太阳能电池 Thin film solar cells 	<ul style="list-style-type: none"> 3D 封装 3D Packaging LED, 平板显示, MEMS LED, FPD & MEMS 封装设计 Packaging Design 芯片可靠性及失效分析 Chip Reliability & Failure Analysis 	<ul style="list-style-type: none"> ※ 华南国际电子生产设备暨微电子工业展 Nepcon South China 深圳/ Shenzhen 8月 ※ 亚洲太阳能与光伏展览会 Asia Solar-Energy & Photovoltaic Exhibition 深圳/ Shenzhen 9月 ※ 中国国际光电博览会 CIOE 深圳/ Shenzhen 9月 ※ Semicon Taiwan 台湾/ Taiwan 9月 ※ 国际太阳能产品及光伏工程展览会 COSPE 北京/ Beijing 9月
<p>10/11</p> <p>Issue date: 20/10 Ad close: 30/9 Mat close: 10/10 Editorial: 20/9</p>	<ul style="list-style-type: none"> 化学机械研磨 CMP 材料 Materials 离子注入 Ion Implantation 平板显示 FPD Technology 	<ul style="list-style-type: none"> LED 封装及测试 LEDs Packaging & Testing 粘接剂 Adhesives 芯片键合与封装 Die Bonding and Encapsulation 晶圆键合/解键合 Wafer Bonding/ Debonding 	<ul style="list-style-type: none"> ※ 中国国际集成电路产业展览暨高峰论坛 IC China 苏州/ Suzhou 10月 ※ 微米纳米技术“创新与产业化”国际研讨与展览会 ICMAN 上海/ Shanghai 11月 ※ 中国太阳能光伏会议暨展览会 China Solar PV 南京/ Nanjing 11月
<p>12/1</p> <p>Issue date: 20/12 Ad close: 1/12 Mat close: 9/12 Editorial: 22/11</p>	<ul style="list-style-type: none"> 原子层沉积 (ALD) Deposition 互连 Interconnect 良率最优化 Yield Optimization 光伏测试技术 PV Test Technology 	<ul style="list-style-type: none"> 芯片堆叠 Die Stacking 引线压焊 Wire Bonding 封装材料 Packaging Materials 封装测试 Packaging Testing 	